Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information	*: Required Field	

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2024-04-10
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	MDG CHAMPION	Representative title	MDGMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

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Legal statement

Supplier acceptance*	true	Legal declaration*	Standard

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

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ACTIVE: 4/16/2024

Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
STM32C011F4P7	D6YA*443XXXZ	A	3068	2024-04-10
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	72	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
1	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Not Applicable	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy	0	
Package designator	Package size	Number of instances	Shape	
TSSOP	4.4x6.5	20	J bend	
Comment	Package : YA TSSOP 20 BODY 4.4 PITCH 0.65 0087225			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false

Exemption Id.	Description
,	

QueryList : REACH-23rd January 2024				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
,	0			

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Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						**Mfr Item Name**	**D6YA*443XXXZ**		71.9500		6000000.0	1000000.0
Homogeneous material	**Material group**	**Mass**	**Unit of measure**	**Level**	**Substance category**	**Substance**	**CAS**	**Exempt**	**Mass**	**Unit of measure**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Die or dies	M-011 Other inorganic materials	4.004	mg	supplier	die	Silicon (Si)	7440-21-3		3.920	mg	979021	54482
				supplier	metallization	Aluminium (Al)	7429-90-5		0.004	mg	999	56
				supplier	metallization	Copper (Cu)	7440-50-8		0.036	mg	8991	500
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.012	mg	2997	167
				supplier	Passivation	Silicon Nitride	12033-89-5		0.009	mg	2248	125
				supplier	Passivation	Silicon Oxide	7631-86-9		0.023	mg	5744	320
Leadframe (C7025 + NiPdAu)	M-011 Other inorganic materials	34.433	mg	supplier	alloy	Copper (Cu)	7440-50-8		32.410	mg	941248	450452
				supplier	alloy	Nickel (Ni)	7440-02-0		1.073	mg	31162	14913
				supplier	alloy	Silicon (Si)	7440-21-3		0.232	mg	6738	3224
				supplier	alloy	Magnesium (Mg)	7439-95-4		0.054	mg	1568	751
				supplier	coating	Nickel (Ni)	7440-02-0		0.647	mg	18790	8992
				supplier	coating	Palladium (Pd)	7440-05-3		0.014	mg	407	195
				supplier	coating	Gold (Au)	7440-57-5		0.003	mg	87	42
Glue eoxy (8601S-25)	M-011 Other inorganic materials	0.848	mg	supplier	glue	Silver (Ag)	7440-22-4		0.745	mg	878000	10348
				supplier	glue	Isobornyl Methacrylate	7534-94-3		0.042	mg	50000	589
				supplier	glue	Urethane Methacrylate Resin	5888-33-5		0.042	mg	50000	589
				supplier	glue	Acrylate polymer	87320-05-6		0.017	mg	20000	236
				supplier	glue	Epoxycyclohexylethyltrimethoxysilane	3388-04-3		0.001	mg	1000	12
				supplier	glue	tert-Butyl peroxy(2-ethyl)-hexanoate	3006-82-4		0.001	mg	1000	12
Bonding wire (CuA)	M-011 Other inorganic materials	0.219	mg	supplier	bonding wire	Copper (Cu)	7440-50-8		0.217	mg	990000	3013
				supplier	bonding wire	Others	Proprietary		0.002	mg	10000	30
Encapsulation (EME-G700KC)	M-011 Other inorganic materials	32.175	mg	supplier	molding compound	Silica, vitreous	60676-86-0		27.952	mg	868745	388490
				supplier	molding compound	Epoxy Resin	85954-11-6		2.364	mg	73464	32852
				supplier	molding compound	Phenol Resin	26834-02-6		1.576	mg	48975	21901
				supplier	molding compound	Carbon black	1333-86-4		0.158	mg	4898	2190
				supplier	molding compound	Bismuth compound	7440-69-9		0.126	mg	3918	1752
Finishing (NiPdAu)	M-011 Other inorganic materials	0.271	mg	supplier	connection coating	Nickel (Ni)	7440-02-0		0.264	mg	974170	3669
				supplier	connection coating	Palladium (Pd)	7440-05-3		0.006	mg	22140	83
				supplier	connection coating	Gold (Au)	7440-57-5		0.001	mg	3690	14

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